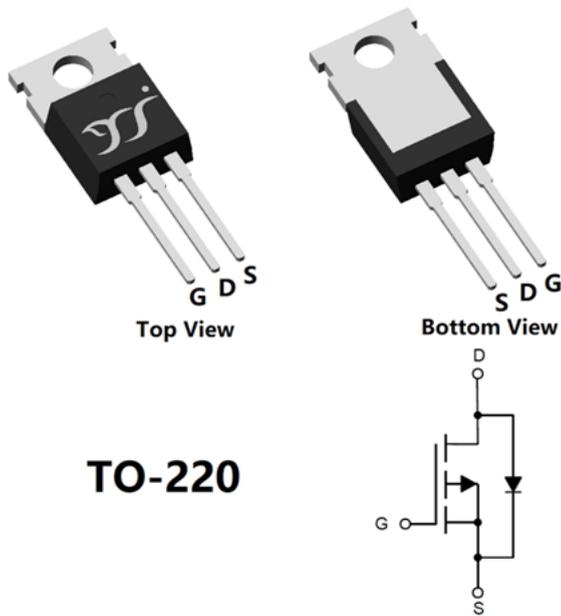


## P-Channel Enhancement Mode Field Effect Transistor



**TO-220**

### Product Summary

- $V_{DS}$  -100V
- $I_D$  -23A
- $R_{DS(ON)}$  (at  $V_{GS}=-10V$ ) <85m $\Omega$
- $R_{DS(ON)}$  (at  $V_{GS}=-4.5V$ ) <100m $\Omega$
- 100% EAS Tested
- 100%  $\nabla V_{DS}$  Tested

### General Description

- Trench Power MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low  $R_{DS(ON)}$
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

### Applications

- Load switch
- Motor drive control
- DC-DC converter

### ■ Absolute Maximum Ratings ( $T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter			Symbol	Limit	Unit	
Drain-source Voltage			$V_{DS}$	-100	V	
Gate-source Voltage			$V_{GS}$	$\pm 20$	V	
Continuous Drain Current (Note 1,2)	Steady-State	$T_A=25^\circ\text{C}, V_{GS}=-10V$	$I_D$	-4.5	A	
		$T_A=100^\circ\text{C}, V_{GS}=-10V$		-2.8		
Continuous Drain Current (Note 1,3)	Steady-State	$T_C=25^\circ\text{C}, V_{GS}=-10V$		-23		
		$T_C=100^\circ\text{C}, V_{GS}=-10V$		-14.5		
Pulsed Drain Current	$T_C=25^\circ\text{C}, t_p=100\mu\text{s}$		$I_{DM}$	-65	A	
Avalanche energy			$V_G=-10V, R_G=25\Omega, L=0.5\text{mH}, I_{AS}=-14.3A$	EAS	51.1	mJ
Total Power Dissipation (Note 1,2)	Steady-State	$T_A=25^\circ\text{C}$	$P_D$	3.5	W	
		$T_A=100^\circ\text{C}$		1.4		
Total Power Dissipation (Note 1,3)	Steady-State	$T_C=25^\circ\text{C}$		125		
		$T_C=100^\circ\text{C}$		50		
Junction and Storage Temperature Range			$T_J, T_{STG}$	-55~+150	$^\circ\text{C}$	

### ■ Thermal resistance

Parameter		Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient (Note 2)	Steady-State	$R_{\theta JA}$	-	35	$^\circ\text{C/W}$
Thermal Resistance Junction-to-Case	Steady-State	$R_{\theta JC}$	-	1	

### ■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJP085P10A	B1	YJP085P10A	50	/	5000	Tube



# YJP085P10A

## ■ Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =-250μA	-100	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-100V, V <sub>GS</sub> =0V	-	-	-1	μA
		V <sub>DS</sub> =-100V, V <sub>GS</sub> =0V, T <sub>J</sub> =150°C	-	-	-100	
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> =0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =-250μA	-1.5	-2	-2.5	V
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-10A	-	65	85	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-5A	-	72	100	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =-10A, V <sub>GS</sub> =0V	-	-	-1.2	V
Gate resistance	R <sub>G</sub>	f=1MHz	-	10	-	Ω
Maximum Body-Diode Continuous Current	I <sub>S</sub>		-	-	-23	A
<b>Dynamic Parameters</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-50V, V <sub>GS</sub> =0V, f=1MHz	-	2065	-	pF
Output Capacitance	C <sub>oss</sub>		-	90	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	72	-	
<b>Switching Parameters</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-50V, I <sub>D</sub> =-10A	-	44.4	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	4.7	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	5.5	-	
Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> =-10A, di/dt=100A/us	-	45	-	nC
Reverse Recovery Time	t <sub>rr</sub>		-	30	-	ns
Turn-on Delay Time	t <sub>D(on)</sub>	V <sub>GS</sub> =-10V, V <sub>DD</sub> =-50V, I <sub>D</sub> =-10A R <sub>GEN</sub> =3Ω	-	9	-	ns
Turn-on Rise Time	t <sub>r</sub>		-	42	-	
Turn-off Delay Time	t <sub>D(off)</sub>		-	91	-	
Turn-off fall Time	t <sub>f</sub>		-	31	-	

Note:

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
2. The value of R<sub>θJA</sub> is measured with the device mounted on the 40mm\*40mm\*1.1mm single layer FR-4 PCB board with 1 in<sup>2</sup> pad of 2oz. Copper, in the still air environment with T<sub>A</sub> =25°C. The maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
3. Thermal resistance from junction to soldering point (on the exposed drain pad).



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## Typical Electrical and Thermal Characteristics Diagrams

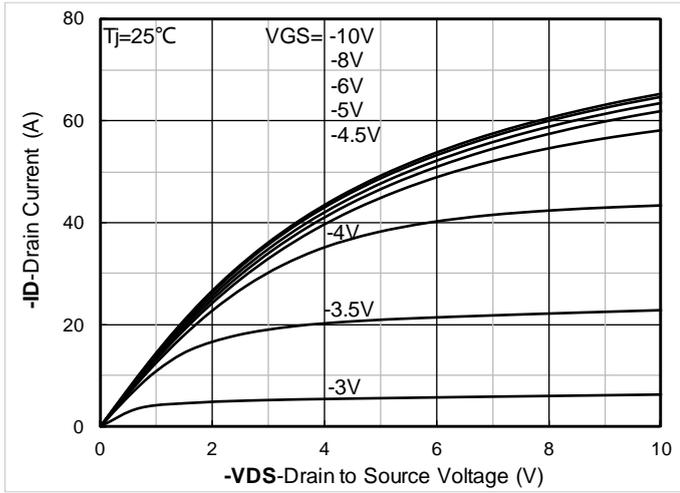


Figure 1. Output Characteristics

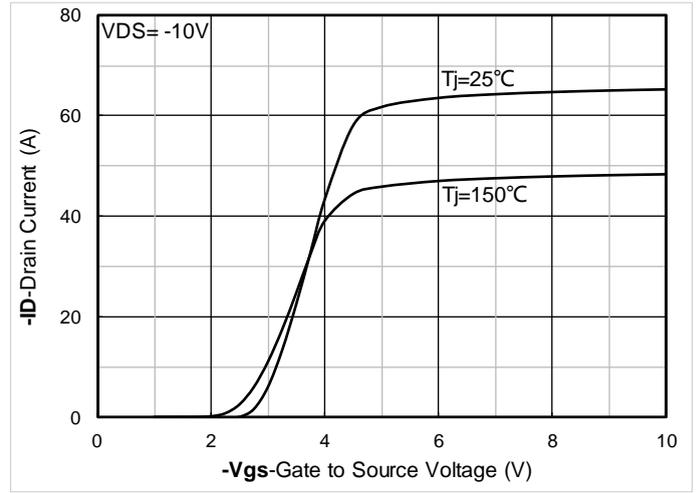


Figure 2. Transfer Characteristics

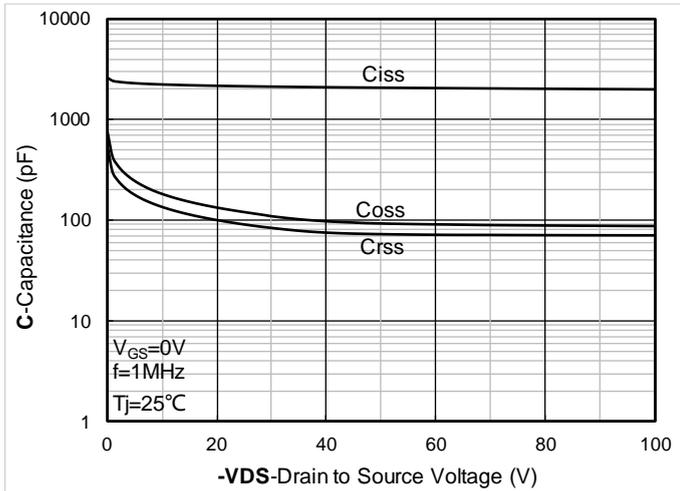


Figure 3. Capacitance Characteristics

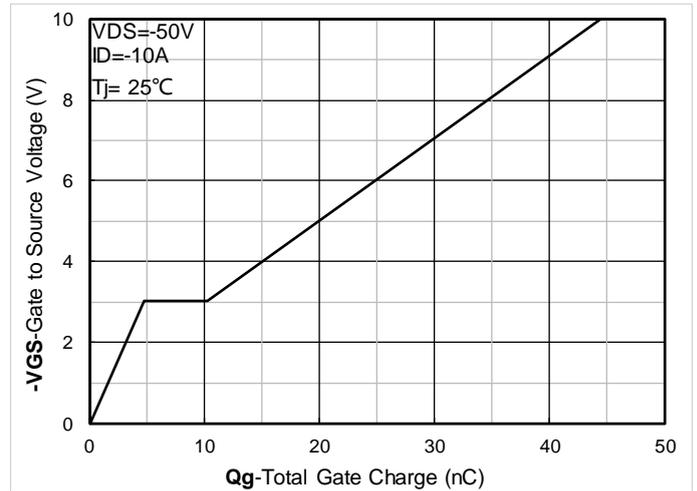


Figure 4. Gate Charge

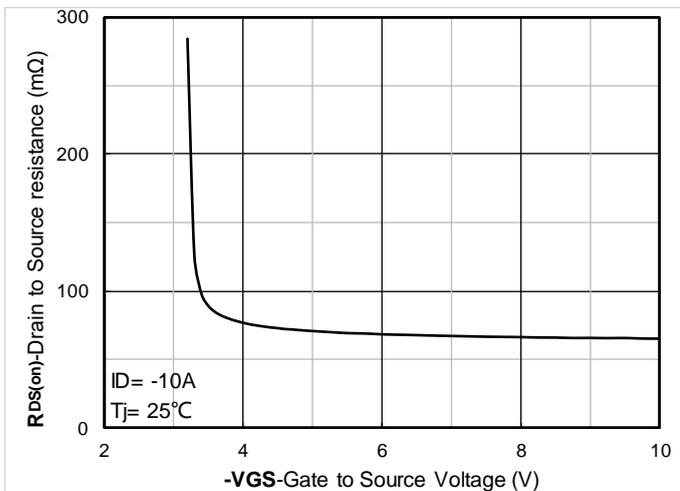


Figure 5. On-Resistance vs Gate to Source Voltage

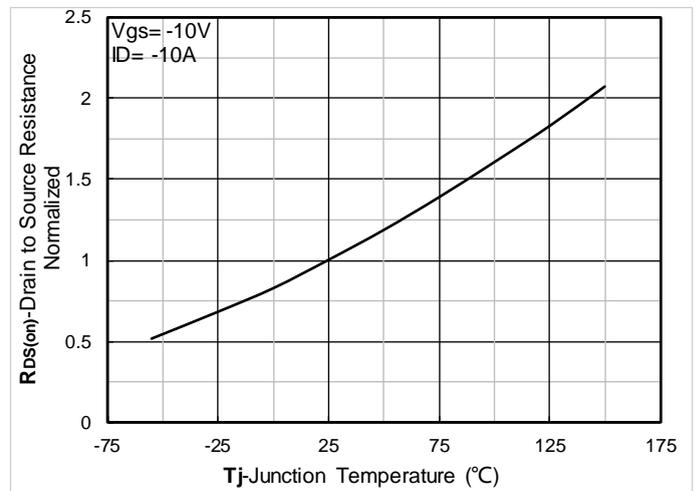


Figure 6. Normalized On-Resistance



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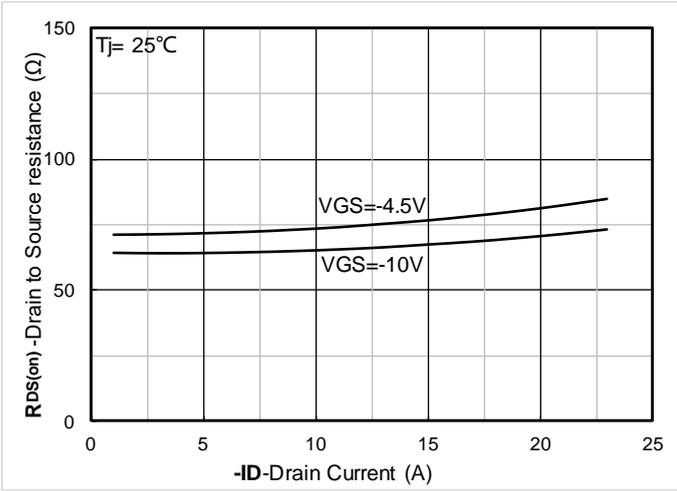


Figure 7.  $R_{DS(on)}$  VS Drain Current

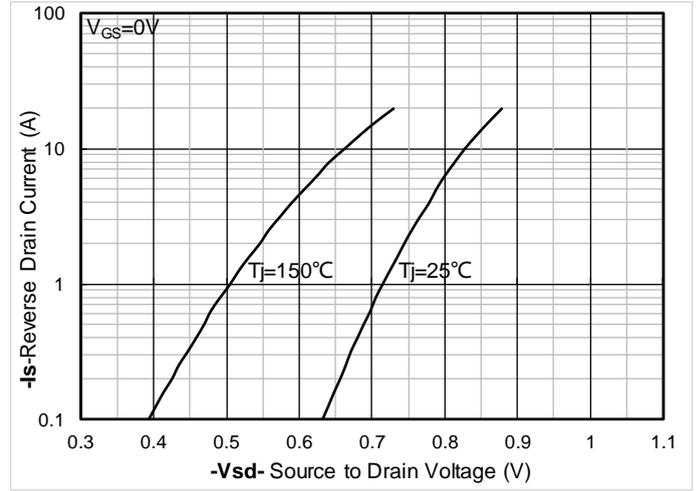


Figure 8. Forward characteristics of reverse diode

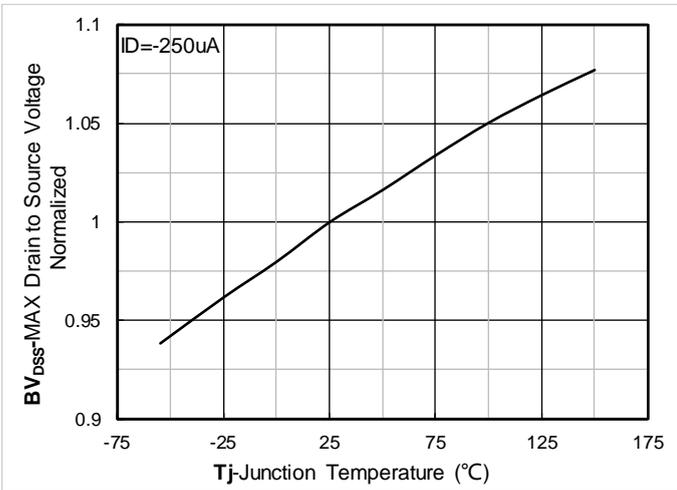


Figure 9. Normalized breakdown voltage

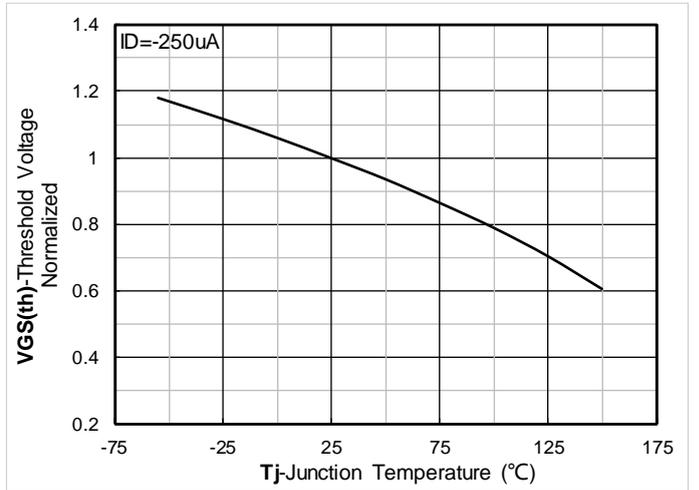


Figure 10. Normalized Threshold voltage

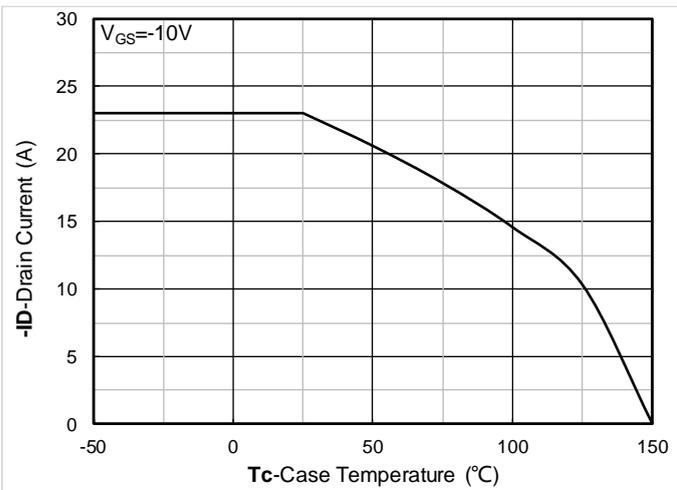


Figure 11. Current dissipation

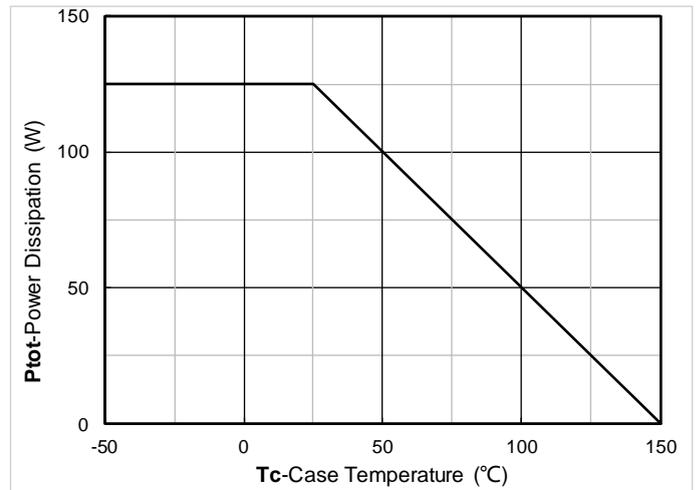


Figure 12. Power dissipation



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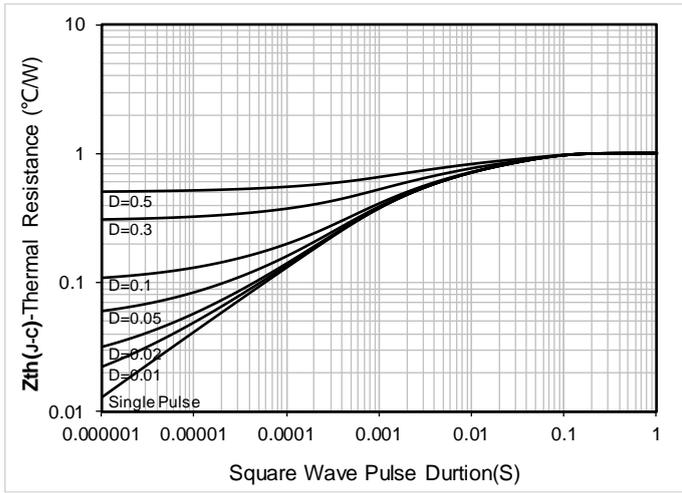


Figure 13. Maximum Transient Thermal Impedance

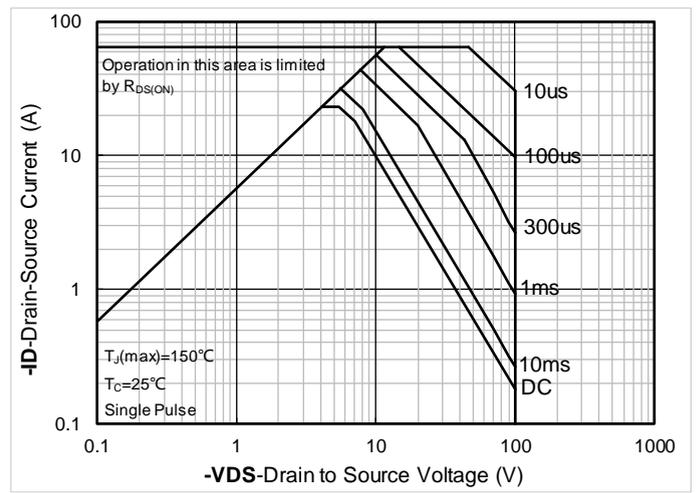
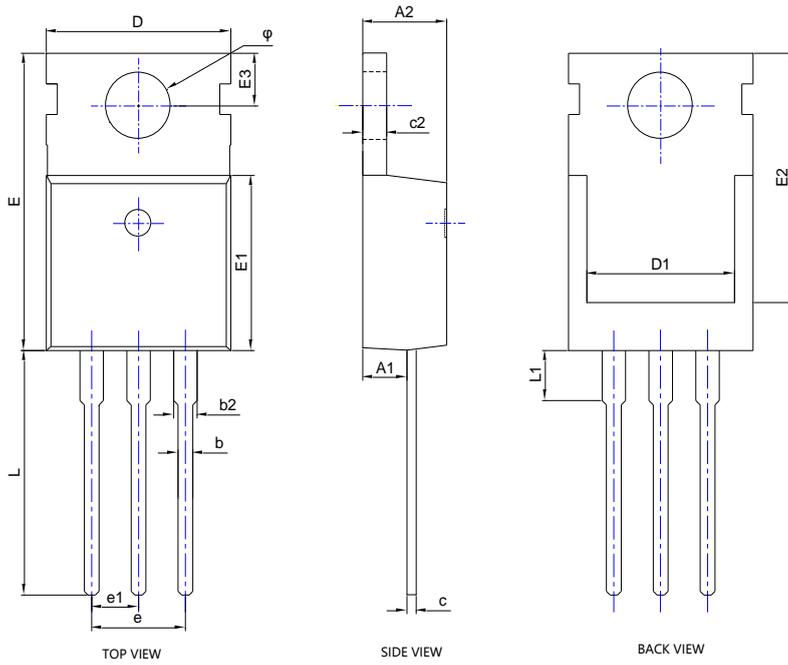


Figure 14. Safe Operation Area



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## ■ TO-220AB-E Package information



SYMBOL	DIMENSIONS			
	INCHES		Millimeter	
	MIN.	MAX.	MIN.	MAX.
A1	0.093	0.114	2.350	2.900
A2	0.176	0.184	4.470	4.670
b	0.028	0.036	0.710	0.910
b2	0.048	0.054	1.220	1.360
c	0.019	0.024	0.470	0.600
c2	0.047	0.055	1.200	1.400
D	0.382	0.408	9.700	10.370
D1	0.276	0.350	7.000	8.890
E	0.579	0.622	14.700	15.800
E1	0.350	0.373	8.900	9.470
E2	0.463	0.535	11.750	13.600
E3	0.108BSC		2.740BSC	
e	0.200BSC		5.080BSC	
e1	0.100BSC		2.540BSC	
L	0.508	0.583	12.900	14.800
L1	0.100	0.151	2.540	3.840
φ	0.142	0.154	3.600	3.900

NOTE:  
 1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.  
 2. TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.



## YJP085P10A

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